

修订记录 / Revised record

描述 / Descriptions

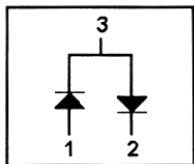
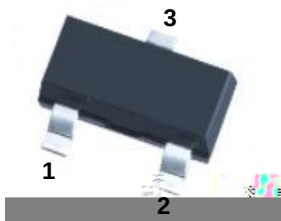
Silicon Diode in a SOT-23 Plastic Package.

特征 / Features

Small signal diode.HF Product.

用途 / Applications

High Conductance Ultra Fast Diode.

内部等效电路 / Equivalent Circuit**引脚排列 / Pinning**

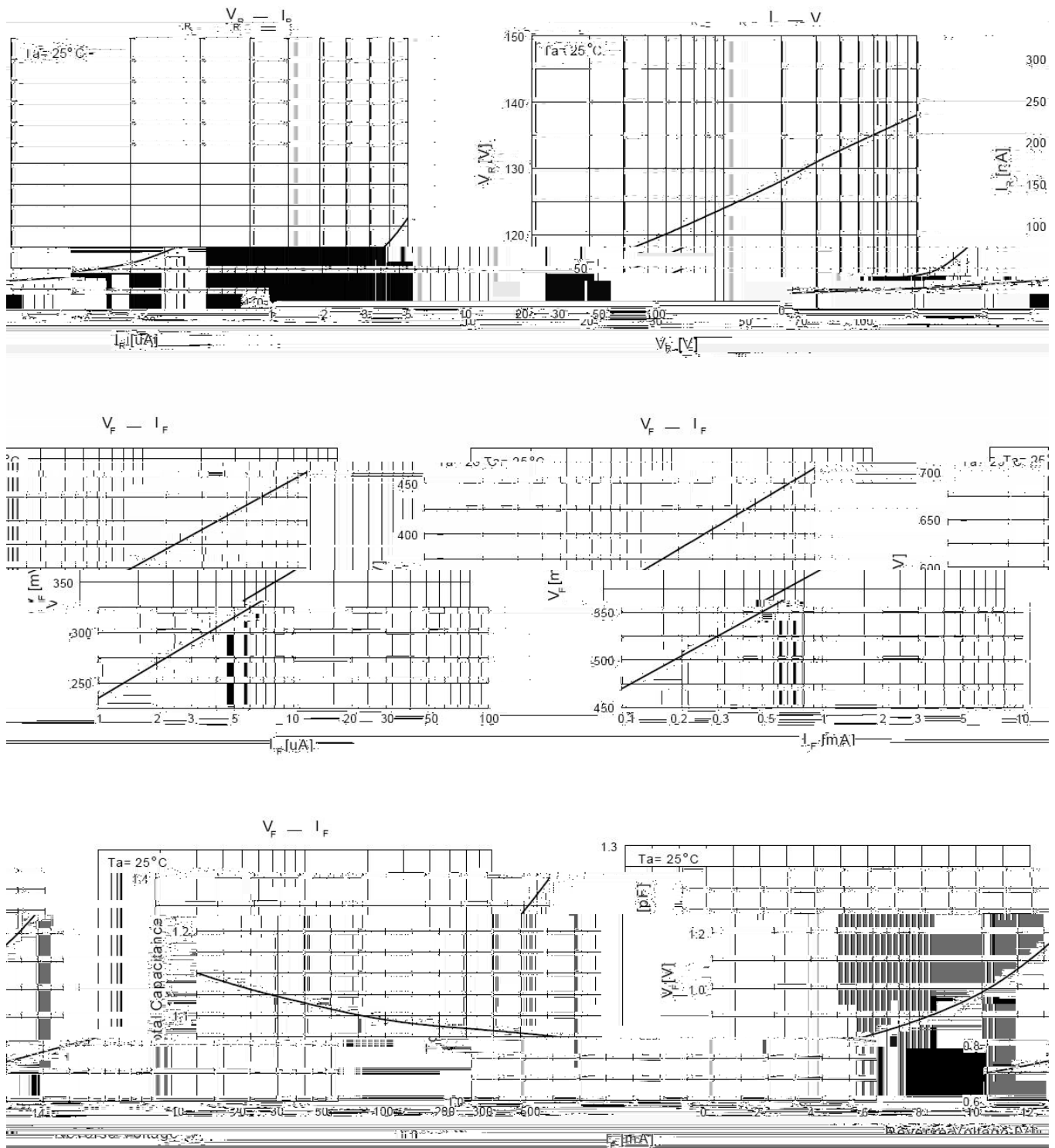
PIN: See Equivalent Circuit.

放大及印章代码 / h_{FE} Classifications & Marking

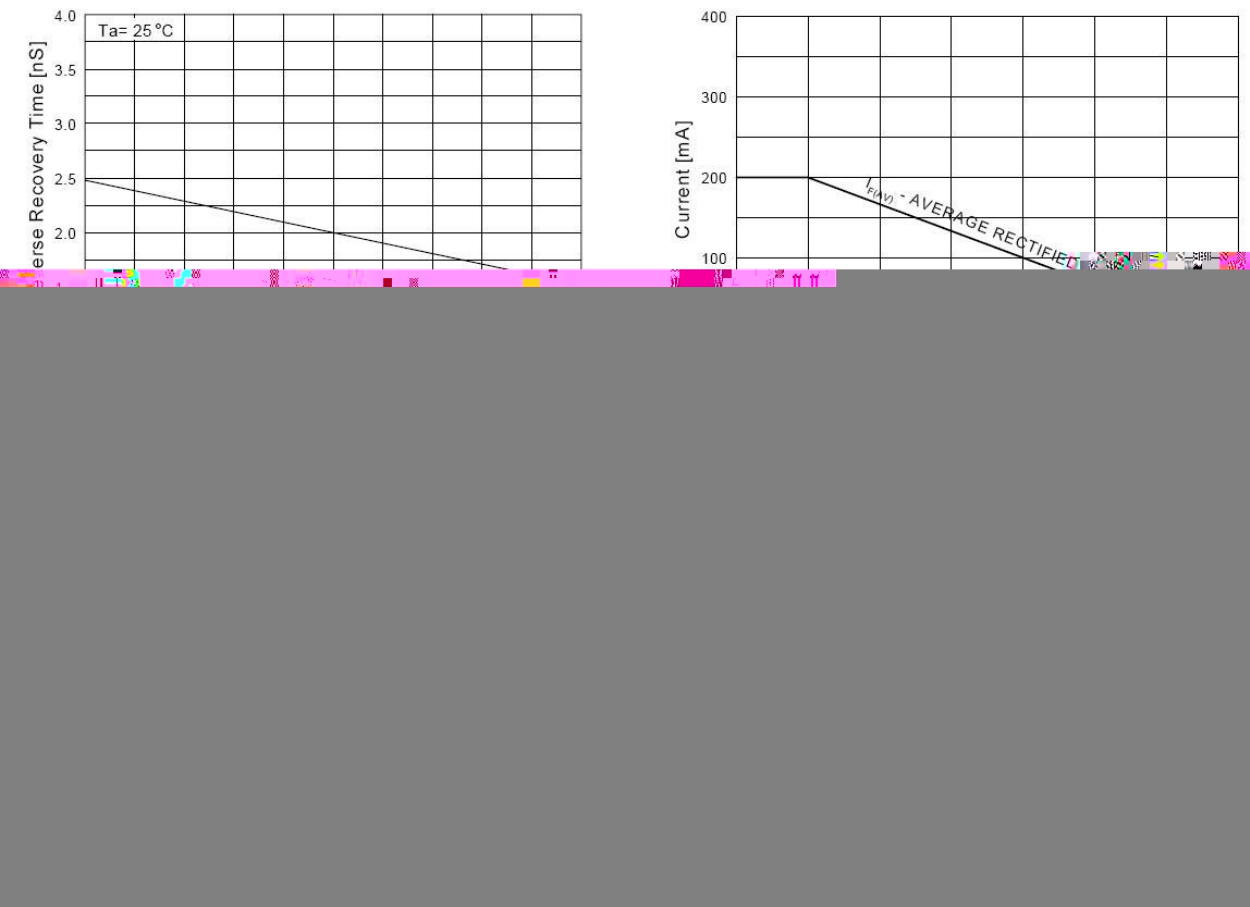
Marking	HA7
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BAV99

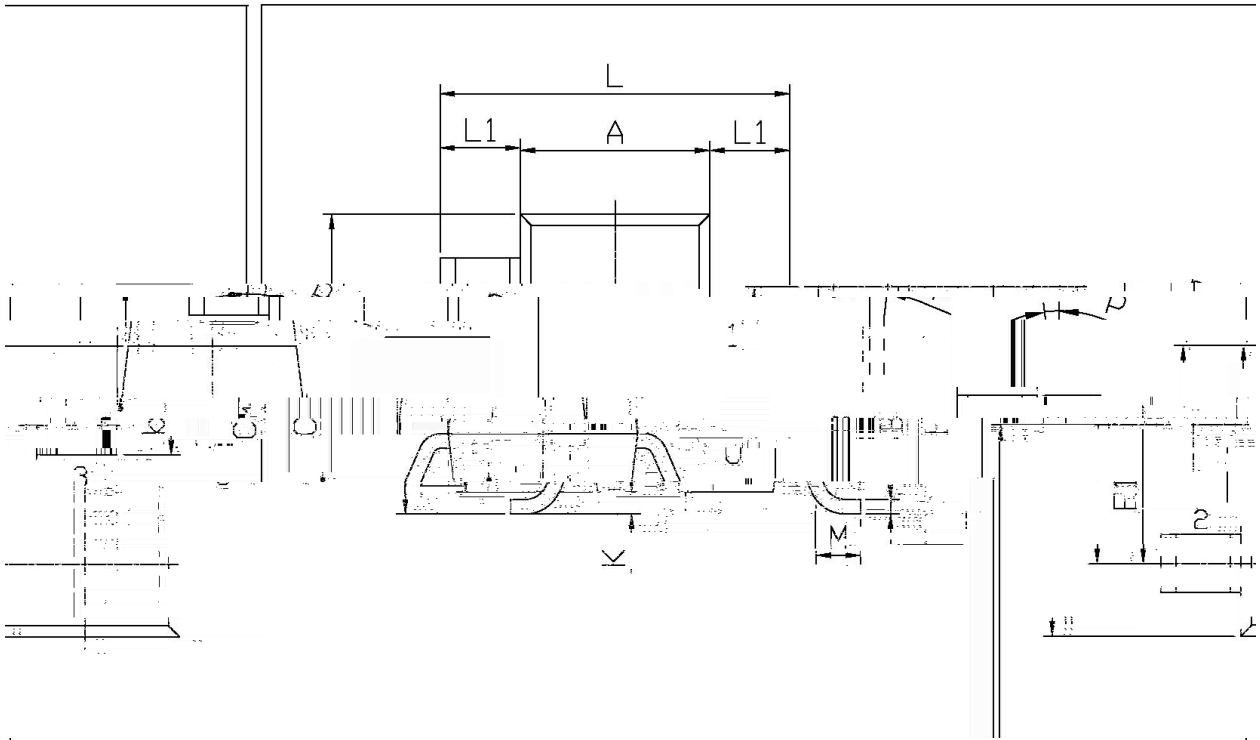
电参数曲线图 / Electrical Characteristic Curve



电参数曲线图 / Electrical Characteristic Curve

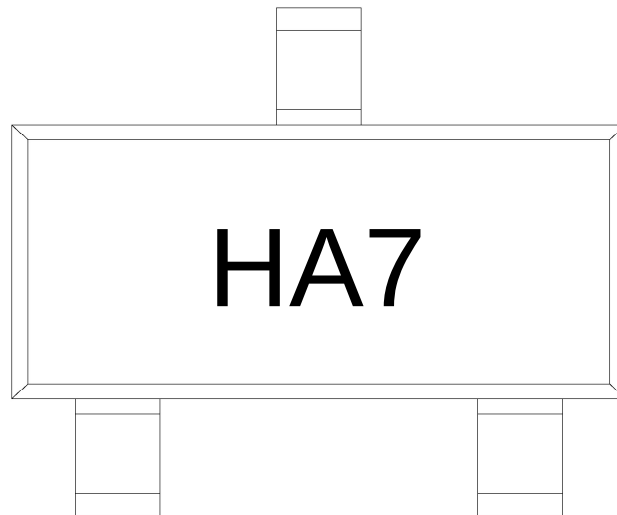


外形尺寸图 / Package Dimensions



Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
L	2.2	2.7	C	1.30Max	
L1	0.45	0.65	C1	0.90	1.20
A	1.15	1.50	E	0.05	0.20
B	2.70	3.10	K	0.10	0.10
D	0.20Min	0.20	E1	0.85	0.85
F	1.05	1.05	b	0.35	0.35
G	0.55	0.55			
H					
I					
J					
K					
M					
N					
P					
Q					
R					
S					
T					
U					
V					
W					
X					
Y					
Z					

印章说明 / Marking Instructions

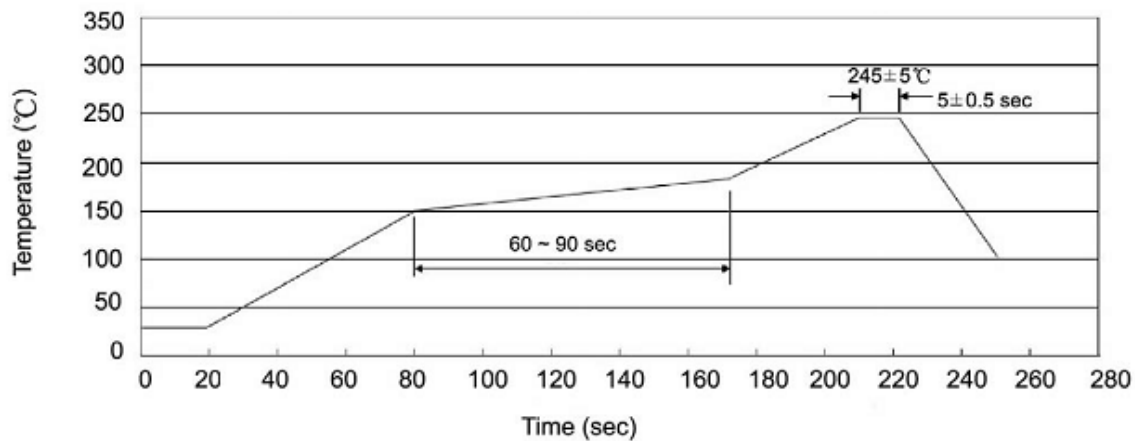


Note:

H: Company Code.

A7: Product Type Code.

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|--------|---|
| 1 | 150 | 180 | 60 | 90sec; | 1.Preheating:150~180 , Time:60~90sec. |
| 2 | 245±5 | | 5±0.5sec; | | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5℃ Time:10±1 sec

包装规格 / Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-23	3,000	10	30,000	6	180,000	7" ×8	180×120×180	390×385×205

使用说明 / Notices